



12-21-01

PATENT  
Attorney Socket No.: 002818/PDD/PSI/JW

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the Application of: Suketu A. Parikh ) Group Art Unit 2813  
 Serial No.: 09/244,788 ) ) Examiner: Pham T.  
 Filed: 2/5/99 ) )  
 For: Dual Damascene Misalignment Tolerant ) )  
 Techniques For Vias And Sacrificial ) )  
 Etch Segments ) )

Assistant Commissioner for Patents  
 Washington, D.C. 20231

Sir:

Transmitted herewith is an **AMENDMENT AND RESPONSE** in the above-identified application, in response to the Office Action mailed 1/18/01. The fee has been calculated as shown below.

	(Col. 1)		(Col. 2)		(Col. 3)	
	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NUMBER PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
TOTAL	23	MINUS	42	0	\$18.00	\$0.00
INDEPENDENT	4	MINUS	6	0	\$84.00	\$0.00
FIRST	PRESENTATION	OF	MULTIPLE DEPENDENT	CLAIM		TOTAL ..\$0.00

\* If the entry in Col.1 is less than the entry in Col.2, "0" is written in Col.3.

\*\* If the "Highest Number Previously Paid for" IN THIS SPACE is less than 20, "20" is written in this space.

\*\*\* If the "Highest Number Previously Paid for" IN THIS SPACE is less than 3, "3" is written in this space.

The "Highest Number Previously Paid For" (Total or Independent is the highest number found from the equivalent box in Col.1 of a prior amendment or the number of claims originally filed.)

No additional Filing Fee is required.  
 Petition to extend time to respond.  
 Extension Fee  
 Other. Please specify:

Please address all correspondence to:

PATENT COUNSEL  
 APPLIED MATERIALS, INC.  
 Legal Affairs Department  
 P.O. Box 450 A  
 Santa Clara, CA 95052

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Date of Deposit Dec. 18, 2001

Signature: Albert J. Dalhuisen  
 Albert J. Dalhuisen

Respectfully Submitted,

By: Albert J. Dalhuisen  
 Albert J. Dalhuisen  
 Registration No.: 36,117

Dated: December 18, 2001

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Attorney Docket No.: 002818/PDD/PSI/JW

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Suketu A. Parikh

Serial No.: 09/244,788

Filed: 2/5/99

For: Dual Damascene Misalignment  
Tolerant Techniques For Vias And  
Sacrificial Etch Segments

- ) Group:
- ) Art Unit: 2813
- ) Examiner: Pham T.
- )
- ) Amendment and Response to Office
- ) Action Mailed 10/18/01
- )
- ) PATENT COUNSEL
- ) APPLIED MATERIALS, INC.
- ) Legal Affairs Department
- ) P.O. Box 450 A
- ) Santa Clara, CA 95052

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

## RESPONSE

This response concerning the above-identified patent application is in response to the Final Rejection Office Action mailed on October 18, 2001.

Clean Amended Claims

Please substitute the following clean amended claims for the pending claims having the same claim number.

5. (once amended) A method of forming a structure on a substrate including at least one interconnect line, the method comprising:

a) depositing a first dielectric layer on the substrate such that there is no material layer interposed between the interconnect line and the substrate;